

## Buck Pulse Width Modulator Stepdown Voltage Regulator

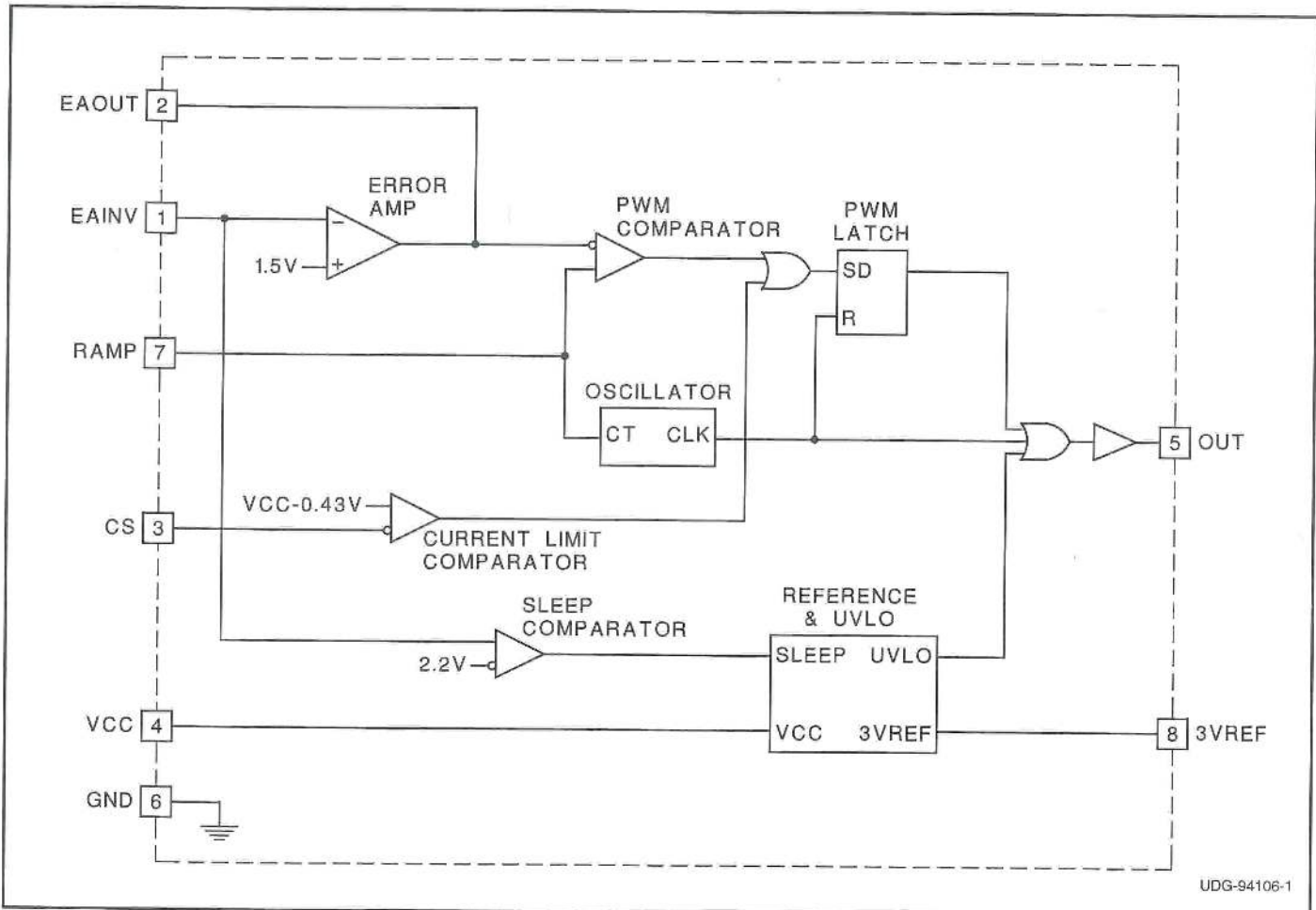
### FEATURES

- Simple Single Inductor Buck PWM Stepdown Voltage Regulation
- Drives External PMOS Switch
- Contains UVLO Circuit
- Includes Pulse-by-Pulse Current Limit
- Low 50 $\mu$ A Sleep Mode Current

### DESCRIPTION

The UC3573 is a Buck pulse width modulator which steps down and regulates a positive input voltage. The chip is optimized for use in a single inductor buck switching converter employing an external PMOS switch. The block diagram consists of a precision reference, an error amplifier configured for voltage mode operation, an oscillator, a PWM comparator with latching logic, and a 0.5A peak gate driver. The UC3573 includes an undervoltage lockout circuit to insure sufficient input supply voltage is present before any switching activity can occur, and a pulse-by-pulse current limit. Input current can be sensed and limited to a user determined maximum value. In addition, a sleep comparator interfaces to the UVLO circuit which turns the chip off when the input voltage is below the UVLO threshold. This reduces the supply current to only 50 $\mu$ A, making the UC3573 ideal for battery powered applications.

### BLOCK DIAGRAM

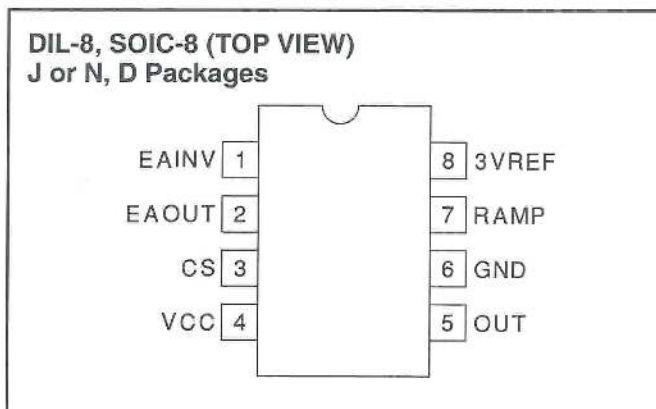


## ABSOLUTE MAXIMUM RATINGS

VCC	35V
EAINV	-0.6V to VCC
IEAOUT	25mA
RAMP	-0.3V to 4V
CS	-0.3V to VCC
IOUT	-0.7A to 0.7A
I <sub>3VREF</sub>	-15mA
Storage Temperature	-65°C to +150°C
Junction Temperature	-65°C to +150°C
Lead Temperature (Soldering, 10 sec.)	+300°C

Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

## CONNECTION DIAGRAMS



**ELECTRICAL CHARACTERISTICS:** Unless otherwise specified, these parameters apply for  $T_A = -55^\circ\text{C}$  to  $+125^\circ\text{C}$  for the UC1573,  $-40^\circ\text{C}$  to  $+85^\circ\text{C}$  for the UC2573, and  $0^\circ\text{C}$  to  $+70^\circ\text{C}$  for the UC3573,  $V_{CC} = 5\text{V}$ ,  $C_T = 680\text{pF}$ ,  $T_A = T_J$ .

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>Reference Section</b>					
3VREF		2.94	3	3.06	V
Line Regulation	$V_{CC} = 4.75$ to $30\text{V}$		1	10	mV
Load Regulation	$I_{3VREF} = 0$ to $-5\text{mA}$		1	10	mV
<b>Oscillator Section</b>					
Frequency	$V_{CC} = 5\text{V}$ , $30\text{V}$	85	100	115	kHz
<b>Error Amp Section</b>					
EAINV	EAOUT = $2\text{V}$	1.45	1.5	1.55	V
IEAINV	EAOUT = $2\text{V}$		-0.2	-1	$\mu\text{A}$
AVOL	EAOUT = $0.5\text{V}$ to $3\text{V}$	65	90		dB
EAOUT High	EAINV = $1.4\text{V}$	3.6	4	4.4	V
EAOUT Low	EAINV = $1.6\text{V}$		0.1	0.2	V
IEAOUT	EAINV = $1.4\text{V}$ , EAOUT = $2\text{V}$	-350	-500		$\mu\text{A}$
	EAINV = $1.6\text{V}$ , EAOUT = $2\text{V}$	7	20		mA
Unity Gain Bandwidth	$T_J = 25^\circ\text{C}$ , $F = 10\text{kHz}$	0.6	1		MHz
<b>Current Sense Comparator Section</b>					
Threshold (referred to VCC)		-0.39	-0.43	-0.47	V
Input Bias Current	CS = VCC		150	800	nA
CS Propagation Delay			400		ns
<b>Gate Drive Output Section</b>					
OUT High Saturation	$I_{OUT} = 0$		0	0.3	V
	$I_{OUT} = -10\text{mA}$		0.7	1.5	V
	$I_{OUT} = -100\text{mA}$		1.5	2.5	V
OUT Low Saturation	$I_{OUT} = 10\text{mA}$		0.1	0.4	V
	$I_{OUT} = 100\text{mA}$		1.5	2.2	V
Rise Time	$T_J = 25^\circ\text{C}$ , $C_{LOAD} = 1\text{nF} + 3.3\text{ Ohms}$		30	80	ns
Fall Time	$T_J = 25^\circ\text{C}$ , $C_{LOAD} = 1\text{nF} + 3.3\text{ Ohms}$		30	80	ns
<b>Pulse Width Modulator Section</b>					
Maximum Duty Cycle	EAINV = $1.4\text{V}$		92	96	%
Minimum Duty Cycle	EAINV = $1.6\text{V}$			0	%
Modulator Gain	EAOUT = $1.5\text{V}$ to $2.5\text{V}$	25	35	45	%/V
<b>Undervoltage Lockout Section</b>					
Start Threshold		3.5	4.2	4.5	V
Hysteresis		100	200	300	mV



**ELECTRICAL CHARACTERISTICS:** Unless otherwise specified, these parameters apply for  $T_A = -55^\circ\text{C}$  to  $+125^\circ\text{C}$  for the UC1573,  $-40^\circ\text{C}$  to  $+85^\circ\text{C}$  for the UC2573, and  $0^\circ\text{C}$  to  $+70^\circ\text{C}$  for the UC3573,  $V_{CC} = 5\text{V}$ ,  $C_T = 680\text{pF}$ ,  $T_A = T_J$ .

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>Sleep Mode Section</b>					
Threshold		1.8	2.2	2.6	V
<b>Supply Current Section</b>					
$I_{VCC}$	$V_{CC} = 30\text{V}$		9	12	mA
$I_{VCC}$	$V_{CC} = 30\text{V}, EAINV = 3\text{V}$		50	150	$\mu\text{A}$

## PIN DESCRIPTIONS

**3VREF:** Precision 3V reference. Bypass with 100nF capacitor.

**CS:** Peak current limit sense pin. Senses the current across a current sense resistor placed between VCC and source of the PMOS Buck switch. OUT will be held high (PMOS buck switch off) if  $V_{CC} - CS$  exceeds 0.4V.

**EAINV:** Inverting input to error amplifier. VOUT sense feedback connected to this pin. The non-inverting input of the error amplifier is internally connected to:

$$\frac{3VREF}{2} \text{ Volts.}$$

Connecting the EAINV pin to an external voltage greater than 2.6V commands the chip to go into a low current sleep mode.

**EAOUT:** Output of error amplifier. Use EAOUT and EAINV for loop compensation components.

**GND:** Circuit Ground.

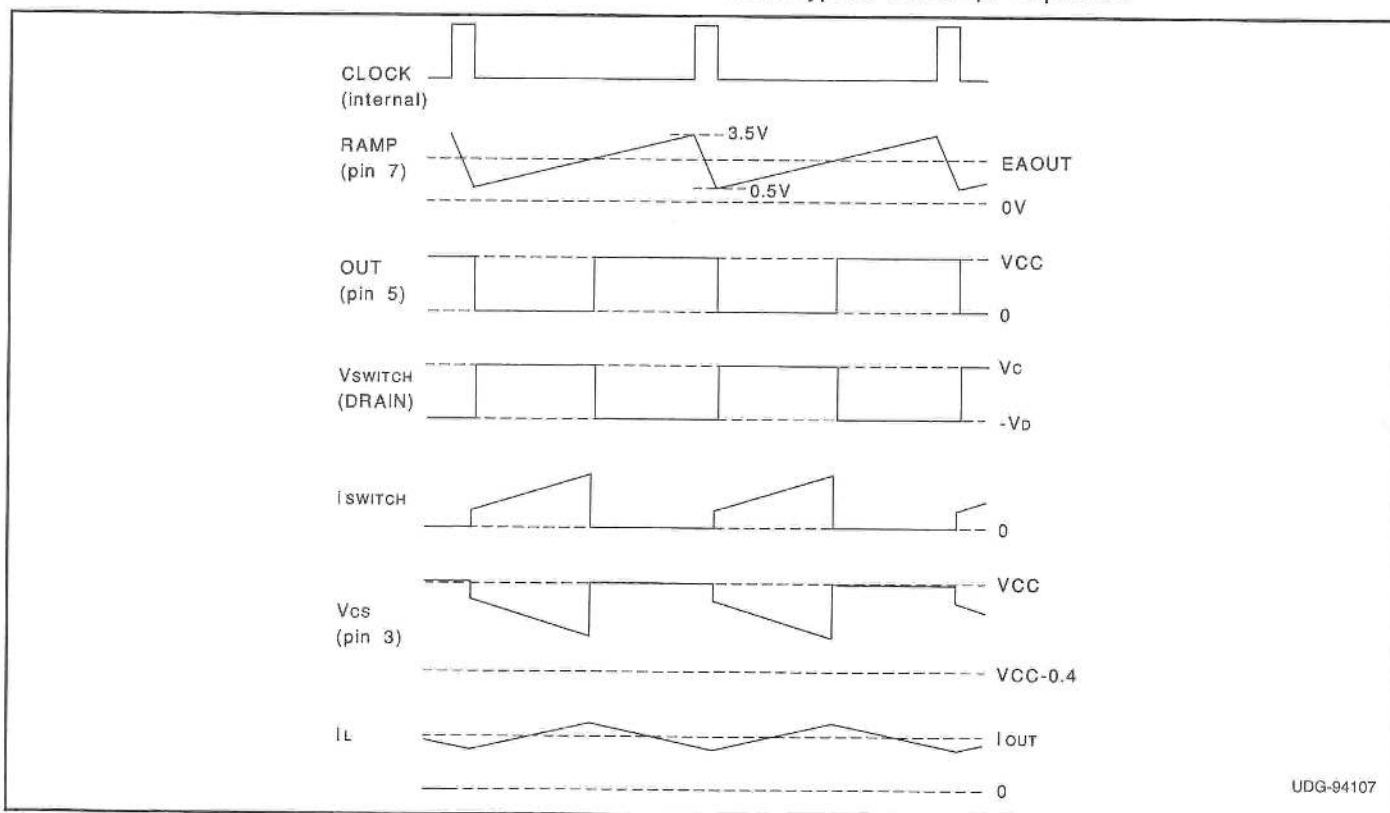
**OUT:** Gate drive for external PMOS switch connected between VCC and the flyback inductor. OUT drives the gate of the PMOS switch between VCC and GND.

**RAMP:** Oscillator and ramp for pulse width modulator. Frequency is set by a capacitor to GND by the equation

$$F = \frac{1}{15k \cdot C_{RAMP}}$$

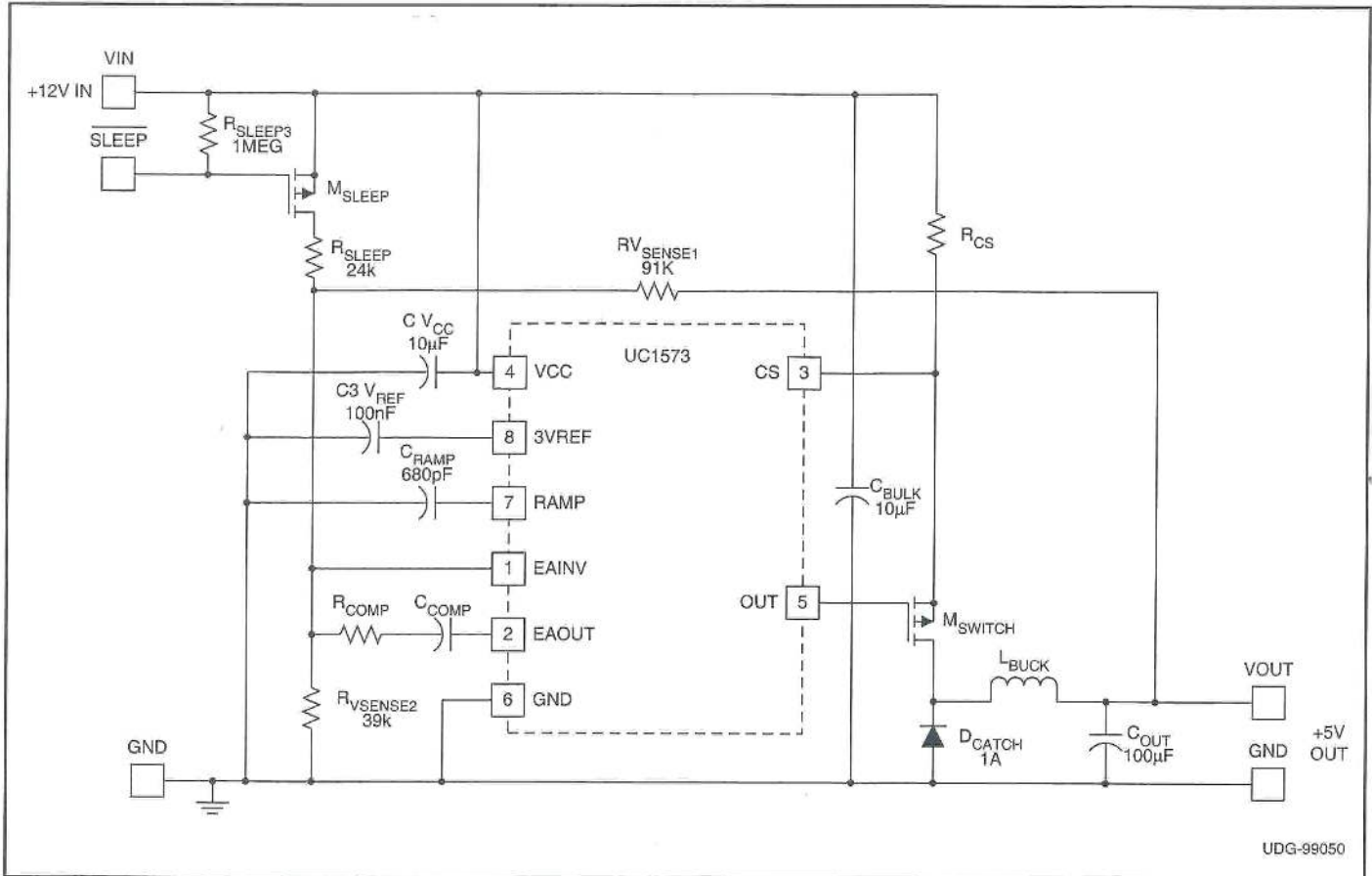
Recommended operating frequency range is 10kHz to 200kHz.

**VCC:** Input voltage supply to chip. Range is 4.75V to 30V. Bypass with a 1 $\mu\text{F}$  capacitor.



Typical Waveforms.

**TYPICAL APPLICATION: 12V TO 5V BUCK CONVERTER**



**REVISION HISTORY**

SLUS346 to SLUS346A, July 2010:

Changed Supply Current I<sub>VCC</sub> units from A to μA

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UC1573J	OBSOLETE	CDIP	J	8		TBD	Call TI	Call TI	-55 to 125		
UC2573D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UC2573D	<a href="#">Samples</a>
UC2573DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UC2573D	<a href="#">Samples</a>
UC2573DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UC2573D	<a href="#">Samples</a>
UC2573DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UC2573D	<a href="#">Samples</a>
UC2573N	NRND	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UC2573N	
UC2573NG4	NRND	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UC2573N	
UC3573D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UC3573D	<a href="#">Samples</a>
UC3573DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UC3573D	<a href="#">Samples</a>
UC3573DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UC3573D	<a href="#">Samples</a>
UC3573DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UC3573D	<a href="#">Samples</a>
UC3573N	NRND	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UC3573N	
UC3573NG4	NRND	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UC3573N	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF UC1573, UC3573 :**

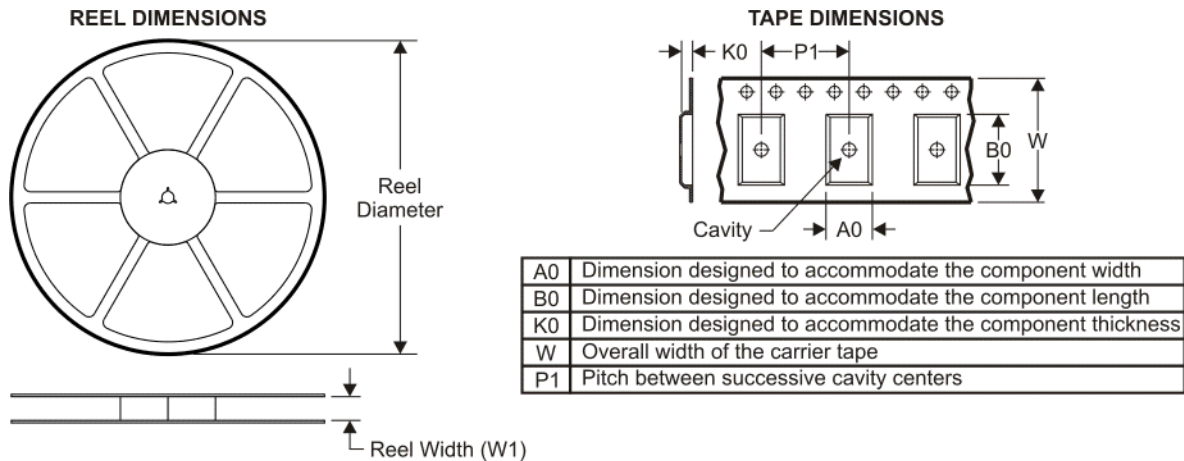
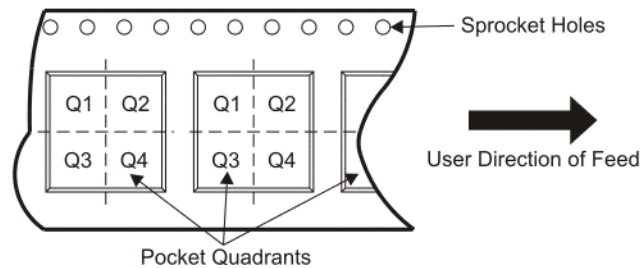
● Catalog: [UC3573](#)

● Military: [UC1573](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2573DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UC3573DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

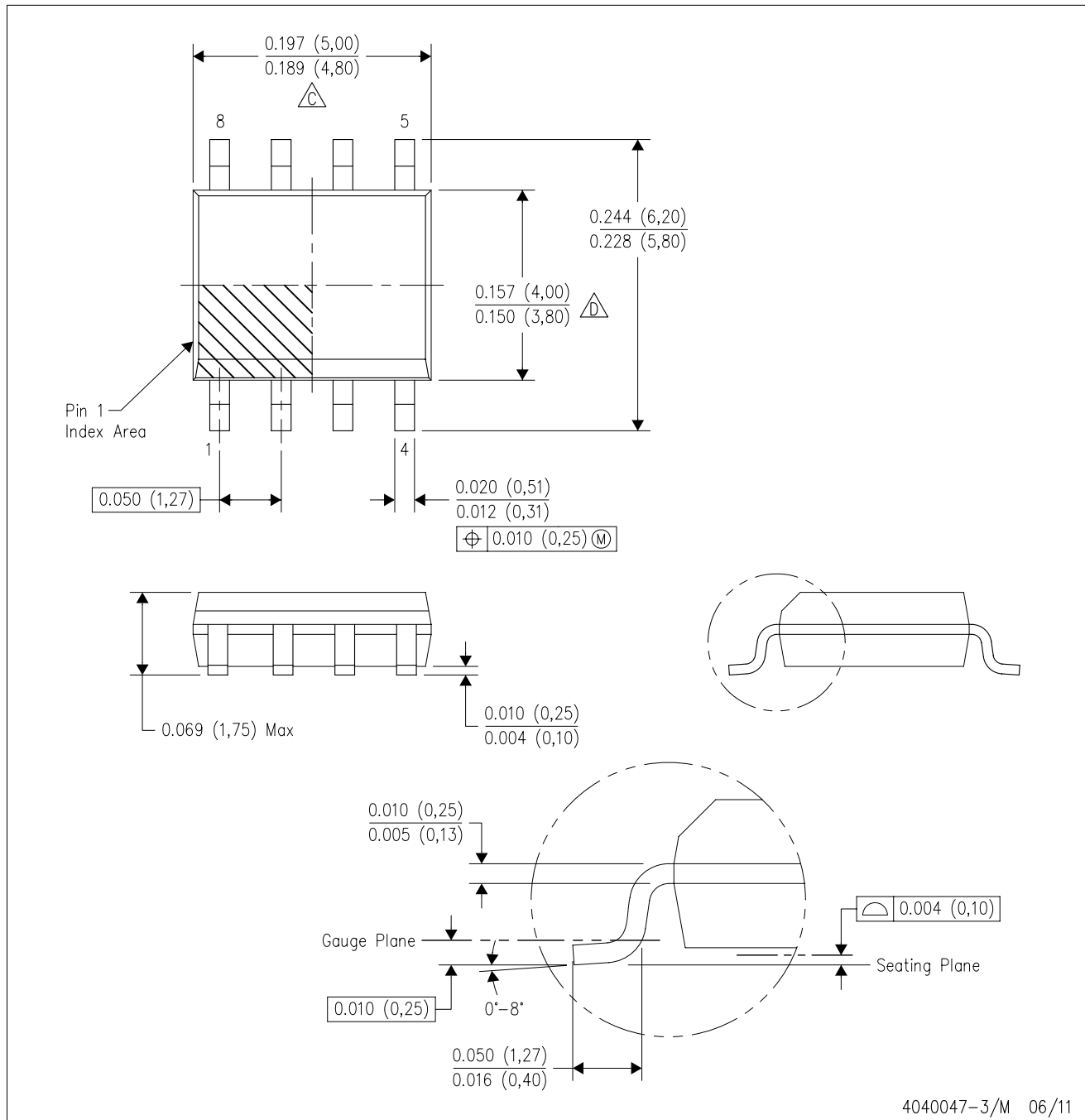
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2573DTR	SOIC	D	8	2500	533.4	338.1	36.0
UC3573DTR	SOIC	D	8	2500	340.5	338.1	20.6





D (R-PDSO-G8)

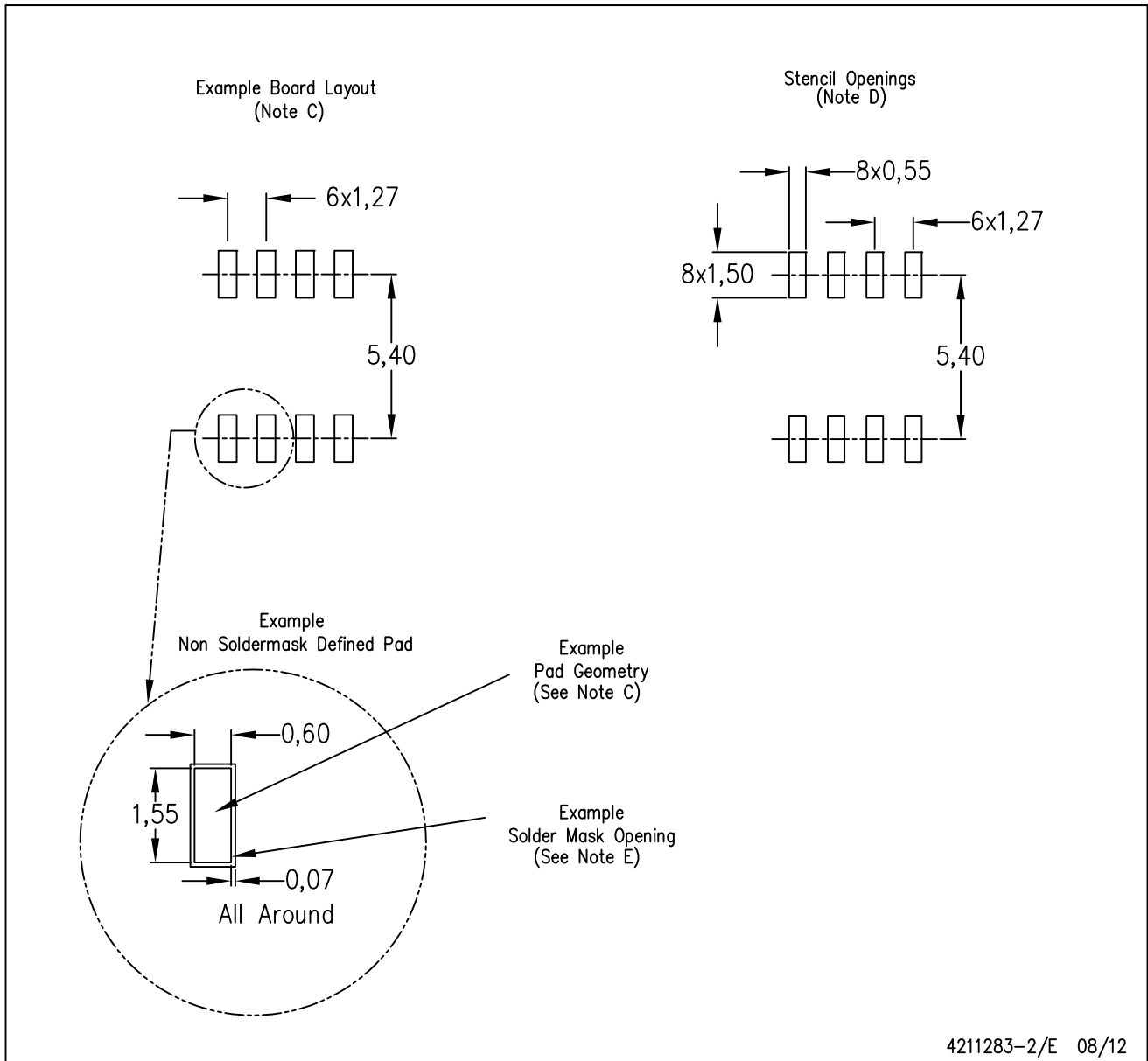
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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